

# Multivalley Electron Conduction at the Indirect-Direct Crossover Point in Highly Tensile-Strained Germanium

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(Received 24 September 2020; revised 2 September 2022; accepted 17 November 2022; published 27 December 2022)

As forward-looking electron devices increasingly adopt high-mobility low-band-gap materials, such as germanium (Ge), questions remain regarding the feasibility of strain engineering in low-band-gap systems. Particularly, the Ge  $L$ - $\Gamma$  valley separation ( $\sim 150$  meV) can be overcome by introducing a high degree of tensile strain ( $\epsilon \geq 1.5\%$ ). It is therefore essential to understand the nature of highly strained Ge transport, wherein multivalley electron conduction becomes a possibility. Here, we report on the competitiveness between  $L$ - and  $\Gamma$ -valley transport in highly tensile-strained ( $\epsilon \sim 1.6\%$ )  $\text{Ge}/\text{In}_{0.24}\text{Ga}_{0.76}\text{As}$  heterostructures. Temperature-dependent magnetotransport analysis reveals two contributing carrier populations, identified as lower- and higher-mobility  $L$ - and  $\Gamma$ -valley electrons (in Ge), using temperature-dependent Boltzmann transport modeling. Coupling this interpretation with electron-cyclotron-resonance studies, the effective mass ( $m^*$ ) of the higher-mobility  $\Gamma$ -valley electrons is probed, revealing  $m^* = (0.049 \pm 0.007)m_e$ . Moreover, a comparison of empirical and theoretical  $m^*$  indicates that these electrons reside primarily in the first-two quantum sublevels of the Ge  $\Gamma$  valley. Consequently, our results provide an insight into the strain-dependent carrier dynamics of Ge, offering alternative pathways toward efficacious strain engineering.

DOI: 10.1103/PhysRevApplied.18.064083

## I. INTRODUCTION

Epitaxial and process-induced strain have been used to enhance the electronic transport properties of silicon (Si) metal-oxide-semiconductor field-effect transistors (MOSFETs) for over a decade [1,2]. In particular, silicon-germanium ( $\text{Si}_{1-x}\text{Ge}_x$ ) alloy source-drain stressors [3,4] and virtual substrates [5] have been utilized to apply compressive strain to the Si channel in  $p$ -MOSFETs, enhancing hole mobility in proportion to the Si/ $\text{Si}_{1-x}\text{Ge}_x$  lattice mismatch (i.e., strain,  $\epsilon$ ). More recently, narrow-band-gap semiconductors, such as germanium (Ge) and III-V ternary alloys (e.g.,  $\text{In}_x\text{Ga}_{1-x}\text{As}$ ), have attracted significant attention due to their enhanced electron and hole mobilities, as compared to Si [6–10]. Similar to Si-based FET architectures, epitaxial and process-induced strain have also

been proposed as methods for enhancing the electronic transport properties of high-mobility semiconductors [11, 12]. Whereas current research predominately focuses on the demonstration of strained Ge (or  $\text{In}_x\text{Ga}_{1-x}\text{As}$ ) FETs [13–15], comparatively little effort [16] is dedicated to elucidating the effects of high-strain states on the electronic transport properties of strained Ge ( $\epsilon$ -Ge) materials. Moreover, the difficulty of such an investigation is compounded by Ge's pseudodirect-band-gap nature, wherein a difference of only about 150 meV separates the  $L$ - and  $\Gamma$ -valley conduction-band minima [11,17–19]. Thus, at high-strain states ( $\epsilon \geq 1.5\%$ ) [18,19], strain-induced modification of the Ge band structure is expected to lower the  $\Gamma$ -valley conduction-band minimum below that of the  $L$  valley, thereby transitioning Ge into a direct-band-gap material with the potential for competitive behavior between the two conduction-band minima to arise [20,21]. However, the density of states (DOS) mass in the  $L$  and  $\Gamma$  valley without strain are  $m_L^{\text{DOS}} = 0.22 m_e$  and  $m_{\Gamma}^{\text{DOS}} = 0.05 m_e$  at room temperature, respectively ( $m_e$  denotes the

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free-electron mass). The DOS mass in the  $L$  valley does not change appreciably, and the  $\Gamma$ -valley DOS mass is reduced from 0.05  $m_e$  at 0% strain to 0.04  $m_e$  at 1.6% biaxial tensile strain. Therefore, the carriers can presumably stay within the  $L$  valley, and by increasing doping along with tensile strain, one can transfer the carriers from the  $L$  valley to the  $\Gamma$  valley. To achieve carrier transport through the  $\Gamma$  valley, it needs to be separated in energy from the  $L$  valley by several tens of meV. Decoupling of the carrier density and mobility from these two valleys as a function of biaxial tensile strain is still elusive, to date, especially enhancement of the mobility for  $L$  electrons. By applying a biaxial tensile strain of about 1.6%, indirect-band-gap Ge is converted into a direct band gap, as demonstrated theoretically using  $\mathbf{k}\cdot\mathbf{p}$  and experimentally [21–23] by low-temperature photoluminescence and photoreflectance measurements. At this strain level, electrons with high mobility can begin to populate the  $\Gamma$  valley, and thus, decoupling of carriers and their mobility is a significant challenge. Thus, the strain-enhanced mobility in  $\varepsilon$ -Ge and relative proportion of carriers in each valley as a function of strain and temperature are of importance. This transport study can find several applications, where carrier density, band offset for carrier confinement, and strain level, which enhance mobility, are all needed for low-power tunnel transistor [24,25], tunnel FET-based memory and logic device [26,27], laser [21,28–30], spintronic [31,32], and qubit [33] applications. In addition, there could be an application in single-electron and quantum devices as well as in cryoelectronics, in which the  $\Gamma$ -electron participation studied here is relevant.

To shed light on these issues, this work exploits the ability of group IV and III-V heterostructures to induce modular tunable epitaxial stress in Ge thin films provided by an underlying III-V strain stressor [25,34,35], thereby enhancing the electronic transport properties of the strained epitaxial Ge layers in a controlled fashion. Utilizing a dual-chamber vacuum-interconnected molecular-beam-epitaxy (MBE) system, we demonstrate the feasibility of integrating low-defect atomically abrupt tensile-strained  $\varepsilon$ -Ge/ $In_xGa_{1-x}As$  heterostructures on lattice-mismatched (001)GaAs substrates. Further characterization of the thin-film  $\varepsilon$ -Ge electronic transport properties and an independent, combined first-principles, and Boltzmann transport calculation framework reveal directly multivalley (i.e.,  $L$  and  $\Gamma$  valleys) conduction in the  $\varepsilon$ -Ge material system. The temperature dependence of the calculated mobility and carrier contributions in the  $L$  and  $\Gamma$  valleys of  $\varepsilon$ -Ge are compared with the experimentally measured results. We also present the direct probing of carrier effective mass in  $\varepsilon$ -Ge under biaxial tensile stress, and from these results, provide evidence for the transition from an indirect to a direct band gap in tensile-strained Ge thin films.

TABLE I. Information on unstrained Ge/AlAs and tensile-strained Ge/ $In_{0.16}Ga_{0.84}As$  and Ge/ $In_{0.24}Ga_{0.76}As$  heterostructures.

Heterostructure	Strain (%)	Ge thickness (nm)
Ge/AlAs/(100)2° GaAs	0	270
Ge/ $In_{0.16}Ga_{0.84}As$ / $In_xGa_{1-x}As$ /(100)2° GaAs	0.75	15
Ge/ $In_{0.24}Ga_{0.76}As$ / $In_xGa_{1-x}As$ /(100)2° GaAs	1.6	30

## II. METHODS

### A. Synthesis and characterization of materials

The unintentionally doped epitaxially unstrained Ge/AlAs and tensile-strained Ge/ $In_xGa_{1-x}As$  (0.75% and 1.6%) heterostructures are grown using an *in situ* dual-chamber MBE growth process. Separate III-V and IV reactors connected *via* an ultrahigh-vacuum transfer chamber allow for isolated growth phases for the  $In_{0.24}Ga_{0.76}As$  (AlAs,  $In_{0.16}Ga_{0.84}As$ ) and unstrained Ge or  $\varepsilon$ -Ge layers, thereby minimizing the likelihood of atomic interdiffusion at the  $\varepsilon$ -Ge/ $In_{0.24}Ga_{0.76}As$  heterointerface (or  $\varepsilon$ -Ge/ $In_{0.16}Ga_{0.84}As$ ) as well as during  $\varepsilon$ -Ge growth. The initial (001) GaAs substrate is offcut 2° towards the (110) direction and desorbed of native oxide at 750 °C under an arsenic (As) overpressure of about  $10^{-5}$  Torr. Here, the (100)/2° GaAs substrate is used for efficient strain relaxation of the graded  $In_xGa_{1-x}As$  buffer layer, which is important for subsequent  $\varepsilon$ -Ge layer growth. The substrate offcut along with growth parameters (growth temperature, growth rate, grading rate, substrate conductivity, etc.) are used to relax the strain energy from the  $In_xGa_{1-x}As$  graded buffer to create a virtual substrate (or template) for subsequent layer growth. Reflection high-energy electron diffraction is used to analyze the surface before, during, and after growth. In the case of the 1.6%  $\varepsilon$ -Ge sample, 0.25 μm of GaAs is grown at 650 °C, followed by a 1-μm linearly graded  $In_xGa_{1-x}As$  buffer and 500-nm  $In_{0.24}Ga_{0.76}As$  stressor grown at 550 °C. The ultrathin 30-nm  $\varepsilon$ -Ge layer is grown at 400 °C using a 0.025 μm/h growth rate to maintain heterointerface abruptness. The growth temperature and growth rate for all other Ge samples are kept constant. Complete details of the growth procedure can be found elsewhere [25]. Table I shows each Ge/III-V heterostructure studied in this work.

Subsequent characterization of the heterostructure's crystal quality, empirical  $In_xGa_{1-x}As$  stressor composition, and epilayer relaxation and strain states is accomplished using high-resolution x-ray diffraction (HRXRD).

The x-ray rocking curves and reciprocal space maps are recorded using a PANalytical X-pert Pro system equipped with PIXcel and proportional detectors and a monochromatic Cu  $K\alpha$  ( $\lambda = 1.540\,597\text{ \AA}$ ) x-ray source. A JY Horiba LabRam HR800 system equipped with a 514.32-nm Ar laser source is used for the collection of Raman spectra and independent corroboration of the  $\varepsilon$ -Ge epitaxial strain. Atomic force microscopy (AFM) micrographs collected with a Bruker Dimension Icon AFM instrument in tapping mode are utilized to analyze the surface morphology of the  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterostructure. Further structural characterization by way of high-resolution cross-section transmission electron microscopy (HRTEM) is performed on a JEOL 2100 TEM instrument and reveals the structural quality,  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterointerface uniformity, and lattice coherence at the strained layer-stressor heterointerface. Additional atomic scale characterization of the  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As interface is performed *via* atomic probe tomography (APT), a combination of time-of-flight spectroscopy and atomic projection imaging that allows for the reconstruction of atomically accurate three-dimensional (3D) ion maps of selected regions of material. Optimization of the measurement conditions utilized herein begins by cooling of the sample to 50 K, followed by a reduction of the laser pulse energy to 3 pJ at a pulse frequency of 250 kHz. The resultant detection rate, approximately 0.01 ions/pulse, is maintained throughout the analysis. We note that the analysis is performed parallel to the  $\langle 001 \rangle$  growth direction. The commercially available IVAST<sup>TM</sup> software is used in the reconstruction of the 3D ion maps.

## B. Electronic and magnetotransport analysis

The unstrained and highly tensile-strained Ge magnetotransport properties, including carrier density and mobility, are measured using Hall measurements under the van der Pauw geometry. In-Sn Ohmic contacts are alloyed on the Ge surface to ensure low-resistance stable electrical contacts at cryogenic temperatures. Temperature-dependent magnetotransport measurements are performed from 0.36 to 5.63 K in magnetic fields up to  $\pm 9$  T using a <sup>3</sup>He cryostat and liquid <sup>3</sup>He submersion and sample-in-vapor cooling. Carrier effective masses for the  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterostructure are extracted from the temperature dependence of Shubnikov-de Haas oscillations in magnetotransport data and independently confirmed *via* electron-cyclotron-resonance analysis. The magnetotransmission measurements necessary for probing the cyclotron-resonance response of the  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterostructure are carried out at the National High Magnetic Field Laboratory using a Fourier-transform infrared spectrometer, superconducting magnet, Globar emission source, and Si bolometer detector.

## C. Calculation of the Ge electronic transport properties under tensile stress

The electronic and band-structure properties of the  $\varepsilon$ -Ge/In<sub>x</sub>Ga<sub>1-x</sub>As heterostructures are theoretically investigated using first-principles calculations that include the effect of strain on Ge material properties. The calculations follow the approach taken by one of the authors for the calculation of transport in Si<sub>1-x</sub>Ge<sub>x</sub> alloys and strained Ge nanostructures, with the addition of changes to the proportion of transport in each valley due to the presence of the (In<sub>x</sub>Ga<sub>1-x</sub>As layer, as explained below. The resulting material parameters are used with the Boltzmann transport equation to determine the *n*-type carrier mobility in the  $\varepsilon$ -Ge layers and examine the population distribution of carriers between the  $L$  and  $\Gamma$  valleys of Ge. The electron–phonon-scattering matrix elements in  $\varepsilon$ -Ge are calculated using first-principles density-functional perturbation theory for intervalley scattering and the frozen-phonon approach for intravalley scattering by acoustic phonons, as in Refs. [20,36] for strained Ge and Si<sub>1-x</sub>Ge<sub>x</sub>. The effects of ionized-impurity scattering are included using the Brooks-Herring approach [37–40]. To ease integration of the transport properties across the Brillouin zone under different strain conditions, we use the first-principles-based  $\mathbf{k}\cdot\mathbf{p}$  analytical form of the electronic band structure of  $\varepsilon$ -Ge after Rideau *et al.* [17]. This  $\mathbf{k}\cdot\mathbf{p}$  approach, unlike the local density approximation in density-functional theory, gives the correct electronic energy gap and dispersion. We correct the temperature dependence of the energy gap and dispersion following the approach of Ref. [37] for strained Si<sub>1-x</sub>Ge<sub>x</sub> (including Ge). The temperature- and alloy-content-dependent mobility of In<sub>x</sub>Ga<sub>1-x</sub>As is obtained from reported experimental values [41].

The effects of quantum confinement follow an envelope-function approach [42], with the boundary conditions given by the empirical  $\varepsilon$ -Ge/In<sub>x</sub>Ga<sub>1-x</sub>As band offsets reported in Ref. [25]. To simplify the calculation, we approximate the heterostructure by a mirror-symmetric In<sub>x</sub>Ga<sub>1-x</sub>As/Ge/In<sub>x</sub>Ga<sub>1-x</sub>As structure, rather than the uncapped case of the experiment. Due to the large band offsets, this approximation allows for much faster computation with little sacrifice to accuracy. The presence of air rather than In<sub>x</sub>Ga<sub>1-x</sub>As at one end would shift the wave function slightly towards In<sub>x</sub>Ga<sub>1-x</sub>As, due to the larger Ge-air band offset. Because the wave function in the In<sub>x</sub>Ga<sub>1-x</sub>As region is so small, we expect the effect on mobility to be very small.

The contribution to the mobility from the Ge  $L$  and  $\Gamma$  valleys and the In<sub>x</sub>Ga<sub>1-x</sub>As  $\Gamma$  valley is given by

$$\begin{aligned} & \mu_{\text{Ge/In}_{0.24}\text{Ga}_{0.76}\text{As}} \\ &= r_{\text{In}_x\text{Ga}_{1-x}\text{As}} \mu_{\text{In}_x\text{Ga}_{1-x}\text{As}} + r_{\text{Ge}^\Gamma} \mu_{\text{Ge}}^\Gamma + r_{\text{Ge}}^L \mu_{\text{Ge}}^L, \end{aligned} \quad (1)$$

where  $\mu_i^j$  is the calculated contribution to the mobility from material  $i$  and valley  $j$ , and  $r_i^j$  is the proportion of carriers in valley  $j$  of material  $i$ , as given by

$$r_i^j = n^j / n_T \sum_b \int_i dz |\psi_b^j(z)|^2, \quad (2)$$

where  $\psi_b^j(z)$  is the  $z$ -direction part of the separable envelope wave function of subband  $b$  of valley  $j$ , and the integral runs only in coordinate  $z$  inside material  $i$ . Coordinate  $z$  denotes the growth and confinement direction. The number of carriers in valley  $j$  is  $n^j$ , out of a total of  $n_T = n^{\text{Ge}} + n^{\text{In}_x\text{Ga}_{1-x}\text{As}}$  carriers.

### III. RESULTS

#### A. Structural properties and relaxation dynamics of the $\varepsilon$ -Ge/ $\text{In}_{0.24}\text{Ga}_{0.76}\text{As}$ system

A cross-section schematic diagram of the  $\varepsilon$ -Ge/ $\text{In}_{0.24}\text{Ga}_{0.76}\text{As}$  heterostructure investigated herein is presented in the left inset of Fig. 1(a). Similarly, the right inset of Fig. 1(a) illustrates the impact of epitaxially induced tensile strain on the (expanded) in-plane and (compressed) out-of-plane lattice constants,  $a$  and  $c$ , respectively, of a coherently strained epilayer (i.e.,  $a_{\text{epi}} = a_{\text{stressor}}$ ). When utilizing  $\text{In}_x\text{Ga}_{1-x}\text{As}$  as a stressor, tailoring of the InAs mole fraction, and therefore,  $a_{\text{In}_x\text{Ga}_{1-x}\text{As}}$ , enables modulation of the lattice strain imparted to an overlying lattice-mismatched film, e.g., Ge. In turn, the electronic and optical properties of the overlying strained epilayer can be tuned within a wide range by varying the amount of strain. As such, a target InAs mole fraction of 0.24 is selected for this work, corresponding to a nominal tensile strain of about 1.63% with respect to relaxed Ge. Such a high-Ge-strain state is predicted to lower the Ge  $\Gamma$ -valley conduction-band minimum below that of the  $L$  valley, resulting in a direct-band-gap Ge material [11,12,18,19].

HRXRD data (Fig. 1) of the as-grown heterostructure reveal that the Ge epilayer is indeed pseudomorphic with respect to the  $\text{In}_x\text{Ga}_{1-x}\text{As}$  virtual substrate (VS). As shown by the symmetric (004) rocking curve (RC) in Fig. 1(a), the strain-induced compression of  $c_{\text{Ge}}$  is observed directly as an increase in the (004) Bragg angle of the  $\varepsilon$ -Ge film (red). For comparison, the (004) RC from a quasi-lattice-matched Ge/GaAs heterostructure is also shown (blue), emphasizing the resultant angular separation between the  $\varepsilon$ -Ge and relaxed Ge diffraction peaks due to strain incorporation. We note that the Pendellösung oscillations observed in the Ge/GaAs RC are not observed on the  $\varepsilon$ -Ge/ $\text{In}_x\text{Ga}_{1-x}\text{As}$  heterostructure, likely owing to disorder-induced x-ray scattering within the dislocation filtering  $\text{In}_x\text{Ga}_{1-x}\text{As}$  linearly graded buffer (LGB) and a thicker excitation volume in the relaxed Ge material rather than a nonabrupt  $\varepsilon$ -Ge/ $\text{In}_x\text{Ga}_{1-x}\text{As}$  heterointerface.

In addition, symmetric (004) and asymmetric (115) reciprocal-space-map (RSM) analysis permits further characterization of the Ge-epilayer-strain state, InAs mole fraction of the  $\text{In}_x\text{Ga}_{1-x}\text{As}$  VS, and relaxation state of the metamorphic buffer. Figures 1(b) and 1(c) show the recorded (004) and (115) RSMs, respectively, highlighting the reciprocal-lattice-point (RLP) centroid for each layer. The  $Q_x$ - $Q_z$  symmetry of the  $\varepsilon$ -Ge RLP suggests uniform crystallinity absent of mosaicity- or defect-related scattering, thereby implying a lack of observable relaxation with the  $\varepsilon$ -Ge epilayer. Likewise, the narrow symmetric nature of the  $\text{In}_x\text{Ga}_{1-x}\text{As}$  VS RLP indicates dislocation-minimal constant-composition epitaxy, signifying a strong confinement of lattice-mismatch-induced defects in the metamorphic LGB and a high amount of buffer relaxation. These observations are quantified following the procedures outlined in Refs. [43,44], as summarily reported in Ref. [25], yielding an  $\text{In}_x\text{Ga}_{1-x}\text{As}$  stressor InAs mole fraction,  $x_{\text{expt.}}$ , of 0.237. From the about 540 arcsec tilt determined *via* the (004) reflection, it can be posited that buffer relaxation

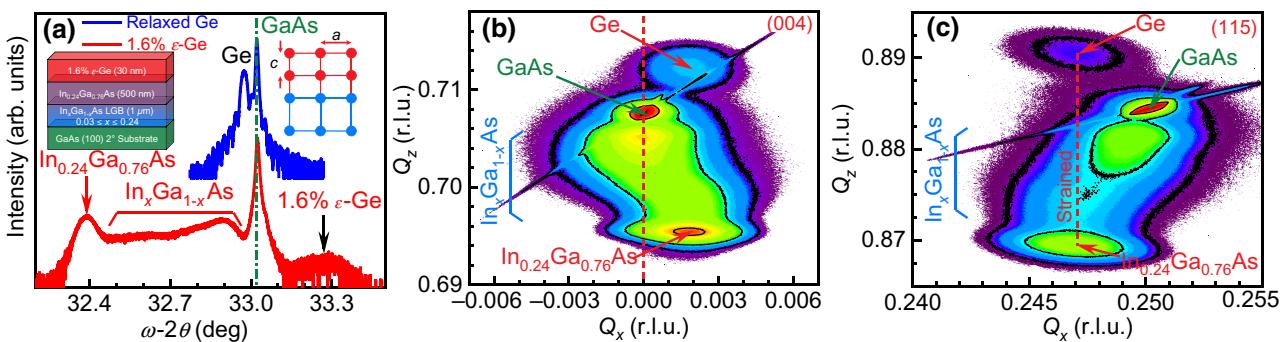


FIG. 1. (a) Symmetric (004)  $\omega$ -2 $\theta$  HRXRD spectra of as-grown  $\varepsilon$ -Ge/ $\text{In}_{0.24}\text{Ga}_{0.76}\text{As}$  heterostructure (red), as compared to a quasi-lattice-matched Ge/GaAs (001) heterostructure (blue). Right inset demonstrates out-of-plane lattice contraction due to corresponding in-plane lattice expansion, whereas left inset provides a cross-section schematic of the  $\varepsilon$ -Ge/ $\text{In}_{0.24}\text{Ga}_{0.76}\text{As}$  heterostructure. High-resolution reciprocal space maps taken along (b) symmetric (004) and (c) asymmetric (115) crystallographic orientations, where (r.l.u.) is reciprocal lattice unit.

occurs in a partially asymmetric nature [45], which is further confirmed *via* the presence of minute, but quantifiable, asymmetries in the  $[1\bar{1}0]$ - and  $[110]$ -oriented surface morphology of the  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterostructure (see Sec. I and Fig. S1 within the Supplemental Material [46–49]). Moreover, the Ge film is found to be 1.6% tensile strained with respect to relaxed (bulk) Ge, indicating near-ideal stress transfer to the Ge lattice and reinforcing the nature of the  $\varepsilon$ -Ge RLP previously discussed.

Raman spectroscopic data (Fig. 2) further confirm the nature of the  $\varepsilon$ -Ge epilayer strain, as demonstrated by the frequency shift observed in the measured  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As Raman spectra. As can be seen in Fig. 2, the  $\varepsilon$ -Ge epilayer (red) exhibits a wave-number shift ( $\Delta\omega$ ) of  $-6.53 \text{ cm}^{-1}$  with respect to the Raman spectra taken from a (001)Ge substrate (blue), resulting in a strain value of  $\varepsilon_{\parallel} = 1.57\%$  [50]. This value is found to be in good agreement with the theoretical misfit for the  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterostructure,  $f \sim 1.63\%$ . Additionally, the relationship between the measured  $\Delta\omega$  and XRD-determined strain ( $\varepsilon_{\parallel}^{\text{XRD}}$ ) is shown in the inset of Fig. 2. Also shown is the expected Raman shift as a function of strain (red) derived using the expression  $\Delta\omega = -b\varepsilon_{\parallel} \text{ cm}^{-1}$  (see Sec. II of the Supplemental Material [46,51–55]). Inclusion of our previously reported results for  $\varepsilon$ -Ge/In<sub>x</sub>Ga<sub>1-x</sub>As heterostructures grown on GaAs (circles) [50] and Si (squares) [53] substrates reveal a strong correlation between the expected  $\Delta\omega$  deduced from  $\varepsilon_{\parallel}^{\text{XRD}}$  and the measured Raman shift (symbols), noting that experimental variance between the measured and expected values is likely to be due to minute strain anisotropies in the  $\varepsilon$ -Ge epilayers as a consequence of the slightly asymmetric nature of the In<sub>x</sub>Ga<sub>1-x</sub>As VS relaxation. These results therefore highlight the applicability of Raman strain analysis to the  $\varepsilon$ -Ge system across a wide range of strain values and substrate platforms and further reinforce the strain-relaxation analysis *via* HRXRD presented earlier.

Low-magnification TEM analysis [Fig. 3(a)] provided additional insight into the relaxation dynamics of the  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterostructure, revealing a dense network of misfit and threading dislocations (TDs) confined within the metamorphic In<sub>x</sub>Ga<sub>1-x</sub>As LGB. Likewise, high-magnification TEM analysis [Fig. 3(b)] demonstrates a highly uniform interface between the  $\varepsilon$ -Ge epilayer and In<sub>0.24</sub>Ga<sub>0.76</sub>As strain template. We note that Fig. 3(b) consists of the as-recorded micrograph superimposed with a noise-filtered image of the same, the effect of which is to enhance image contrast in the vicinity of atomic columns. Utilization of this two-step FFT noise-filtering approach [i.e.,  $F^{-1}(F(k))$ ] suggests an atomically abrupt heterointerface lacking substantial atomic interdiffusion. In the next section, we provide definitive evidence for this conclusion *via* APT. More localized FFT patterns captured from representative  $14 \times 14 \text{ nm}^2$  regions of the (i)  $\varepsilon$ -Ge epilayer, (ii)  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterointerface,

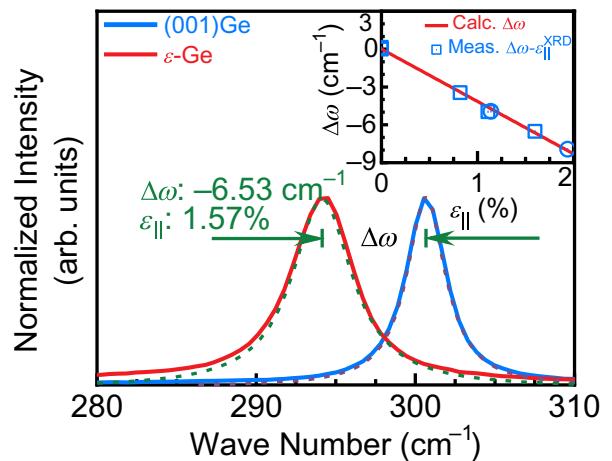


FIG. 2. Raman spectra collected for (001) Ge substrate (blue) and  $\varepsilon$ -Ge epilayer grown on In<sub>0.24</sub>Ga<sub>0.76</sub>As (red). Inset highlights the relationship between the expected Raman wave-number shift (solid line, red) and the HRXRD-determined tensile strain (symbols, blue).

and (iii) In<sub>0.24</sub>Ga<sub>0.76</sub>As strain template are shown in Figs. 3(c)–3(e), respectively. The indistinguishable nature of the FFT patterns across the heterointerface and the absence of satellite reflections indicate the major contribution of a single lattice parameter to the diffractogram, thereby providing ancillary support for a quasi-ideal pseudomorphic Ge epitaxy.

Figure 3(f) shows a plan-view TEM micrograph taken from a beveled sample foil (bottom-left inset) under the  $g = (2\bar{2}\bar{0})$  diffraction condition. Utilizing plan-view TEM analysis permits a conservative estimation of the TD density in the In<sub>0.24</sub>Ga<sub>0.76</sub>As stressor,  $\rho_{\text{TDD}} \leq 2 \times 10^7 \text{ cm}^{-2}$  (see Sec. III of the Supplemental Material [46,56–59]); notably, TDs are only observed upon etching of the  $\varepsilon$ -Ge epilayer. Additionally, Fig. 3(f) reveals an abrupt termination in the In<sub>0.24</sub>Ga<sub>0.76</sub>As misfit dislocation (MD) network, which is posited to occur at the  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterointerface. This is conclusively demonstrated by FFT analysis of the {111} planes in the vicinity of the interface, as shown in the insets of Fig. 3(b). MDs exhibiting the insertion of an extra half-plane of atoms (i.e., edge dislocations) are observed; notably, positive and negative edge dislocations are found in both the  $\varepsilon$ -Ge and In<sub>0.24</sub>Ga<sub>0.76</sub>As stressor layers. Moreover, these MDs are confined to within 4 nm of the heterointerface and exhibit aperiodic MD spacing. Correlating these results with the previously discussed HRXRD analysis, the lack of quantifiable tilt in the (004)  $\varepsilon$ -Ge RLP (with respect to the In<sub>0.24</sub>Ga<sub>0.76</sub>As stressor) suggests that these are 90° MDs. It is generally understood that, under tensile strain, it is energetically favorable for perfect 60° dislocations to disassociate into leading 90° and trailing 30° partial dislocations (see Sec. III and Fig. S2 within the Supplemental Material) [46,56]. Given the

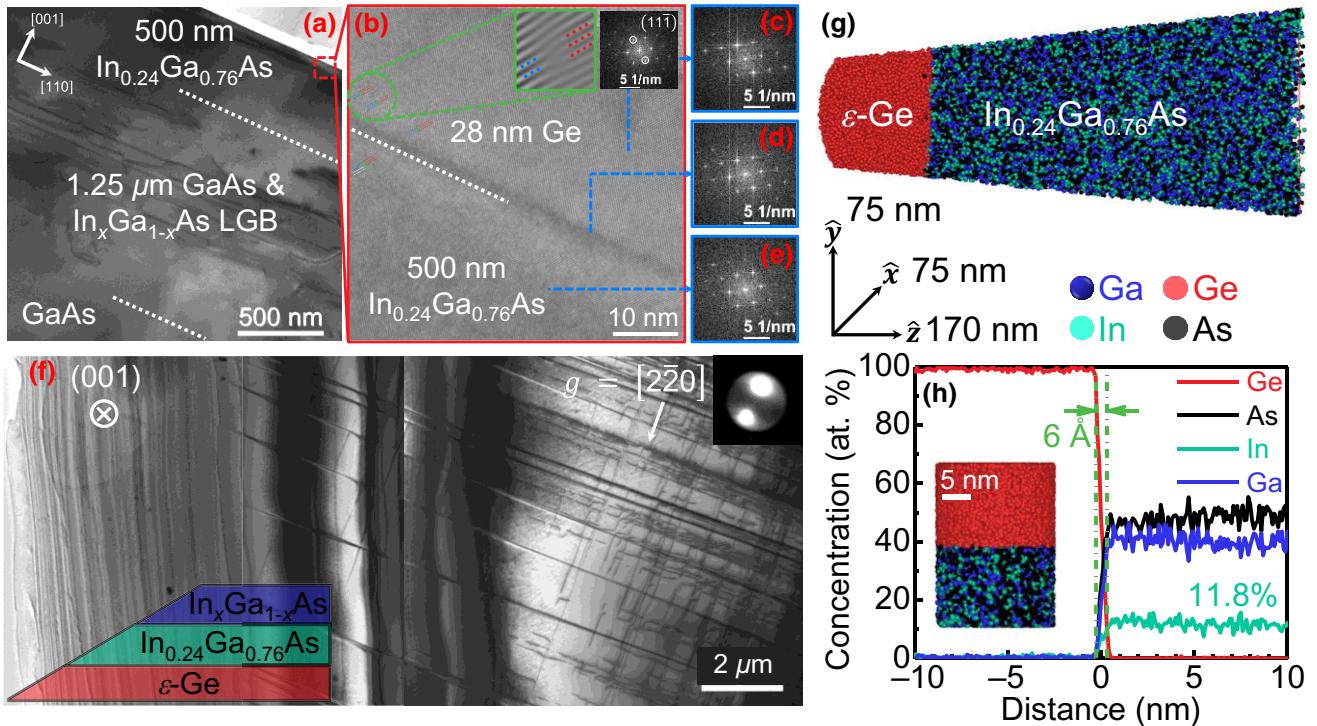


FIG. 3. (a) Low-magnification cross-section transmission electron micrograph (XTEM) of the entire  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As/In<sub>x</sub>Ga<sub>1-x</sub>As/GaAs (001) heterostructure. (b) High-magnification XTEM of the  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterointerface, and (c)–(e) associated fast Fourier transform (FFT) patterns. Insets display the  $11\bar{1}$  crystallographic plane and corresponding reciprocal space reflections used in the misfit dislocation analysis. (f) Low-magnification plan-view TEM of a beveled  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As sample and corresponding representative cross-section schematic (bottom-left inset). (g) Reconstructed 3D atom-probe tomographic ion map of a representative  $75 \times 75 \times 170$  nm<sup>3</sup> conical volume taken from the as-grown  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterostructure and (h) associated atomic concentration depth profile. Inset of (h) corresponds to the region from which the atomic concentration depth profile is generated.

irregular MD spacing observed in Fig. 3(b) and the localization of MDs in  $\varepsilon$ -Ge to corresponding dislocations in the In<sub>0.24</sub>Ga<sub>0.76</sub>As stressor, it is therefore likely that the observed MDs are 90° partial dislocations that form during Ge epilayer growth. Indeed, a Burgers circuit traced around a representative dislocation core (see Fig. S2(d) within the Supplemental Material [46]) reveals the formation of the stacking fault associated with the nucleation of a 90° partial dislocation having a projected Burgers vector of  $(a_0/6)\langle 112 \rangle$ . Thus, as no quantifiable  $\rho_{TDD}$  is observed in the  $\varepsilon$ -Ge epilayer, we posit that the high strain energy at the Ge surface during growth results in enhanced TD glide at the  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterointerface, thereby preventing vertical TD propagation and accommodating strain relaxation through the formation and disassociation of perfect 60° MDs into leading 90° partial dislocations [60].

Lastly, independent corroboration of the  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterointerface abruptness is provided by APT, which is used to reconstruct atomically accurate 3D ion maps of representative  $75 \times 75 \times 170$  nm<sup>3</sup> (conical) volumes of the as-grown  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterostructure. Figure 3(g) shows one such reconstructed 3D ion map,

wherein individual gallium (Ga), indium (In), arsenic (As), and Ge atoms are depicted in blue, green, black, and red, respectively. Likewise, a magnified region in the vicinity of the  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterointerface [Fig. 3(h), inset] is used to generate a representative atomic concentration depth profile [Fig. 3(h)]. Measurement of the separation between the 90% and 10% atomic thresholds for a given ion species allows for an estimation of the atomic interdiffusion at the  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterointerface. Explicitly, no quantifiable atomic interdiffusion occurs beyond an initial 6-Å diffuse region formed at the onset of Ge nucleation. This result can be explained by a combination of the low-temperature and low-growth-rate Ge epitaxy conditions utilized in this work. The former is expected to minimize As surface desorption from the In<sub>x</sub>Ga<sub>1-x</sub>As surface prior to and during Ge nucleation, whereas the latter promotes uniform Ge surface coverage during nucleation and subsequent Frank-van der Merwe-dominated epitaxy. When taken together, these two processes reduce the likelihood of As out-diffusion into the growing Ge epilayer, consequently preserving heterointerfacial uniformity and abruptness. Finally, we

note that the InAs mole fraction of the  $\text{In}_x\text{Ga}_{1-x}\text{As}$  virtual substrate, as determined *via* APT analysis, is 0.236 (11.8 atomic %), which is in excellent agreement with the HRXRD results outlined earlier.

## B. Electronic and magnetotransport properties of highly tensile-strained Ge

Having demonstrated the successful integration of highly tensile-strained Ge on  $\text{In}_x\text{Ga}_{1-x}\text{As}$  strain templates, we now turn our attention to the carrier dynamics of such heterostructures. To this end, the magnetotransport properties of the  $\varepsilon$ -Ge/ $\text{In}_{0.24}\text{Ga}_{0.76}\text{As}$  heterostructure are measured in a van der Pauw configuration with a magnetic field,  $B$ , applied perpendicularly to the (001) growth direction and at temperatures ranging from 0.36 to 5.63 K. Magnetotransport data consist of transverse magnetoresistance [ $R_{xy}(B)$ , Hall effect] and longitudinal magnetoresistance. The latter is extracted by symmetrization of data obtained for the two polarities of  $B$ , since longitudinal magnetoresistance must be symmetric with respect to applied  $B$ . Figure 4(a) presents  $R_{xy}(B)$  versus  $B$  obtained at different measurement temperatures. From the slope of the linear region (over  $\pm 2$  T), an areal carrier density of  $N_{S1} = 8.50 \times 10^{16} \text{ m}^{-2}$  is deduced, which is substantially constant over the measured temperature range. The sign of the slope indicates that electrons are at the origin of this Hall effect. Additionally, Shubnikov-de Haas oscillations are observed at higher  $B$ , superimposed on the Hall effect, and exhibiting a pronounced dependence on temperature. The Shubnikov-de Haas oscillations are observed in this van der Pauw geometry owing to mixing of  $R_{xy}(B)$  with residual longitudinal magnetoresistance. As their origin lies in longitudinal magnetoresistance, the Shubnikov-de Haas oscillations can be extracted by symmetrization in  $B$  of the data. Figure 4(b) shows the longitudinal magnetoresistance after the subtraction of a background to yield the oscillatory part ( $\Delta R$ ) and its

subsequent normalization by the sheet resistance ( $R_0$ ). The Shubnikov-de Haas oscillations exhibit a clear periodicity in inverse  $B$ , from which  $B^{-1}$  taken at the maxima versus the index of the maxima (arbitrarily starting with index 1 at  $B = 0.16 \text{ T}^{-1}$ ) is displayed in Fig. 4(c), resulting in a monotonic trend line with slope  $S = (0.0853 \pm 0.001) \text{ T}^{-1}$ . An areal density,  $N_{S2}$ , is deduced from  $S$  [61,62], using the relationship  $N_{S2} = e/(\pi \hbar S)$ , where  $e$  denotes the electron charge and  $\hbar$  is Planck's constant, yielding  $N_{S2} = (5.67 \pm 0.06) \times 10^{15} \text{ m}^{-2}$ . Here, we assume negligible Zeeman splitting, and hence, spin degeneracy. Whether the carriers giving rise to the Shubnikov-de Haas oscillations are electrons or holes cannot be ascertained. Yet Shubnikov-de Haas oscillations require minimal broadening of Landau levels, implying that this carrier population ( $N_{S2}$ ) has higher mobility than the population giving rise to the Hall effect ( $N_{S1}$ ), which cannot be detected in the Shubnikov-de Haas oscillations. From the dependence on temperature of the oscillations in Fig. 4(b), an effective mass is extracted using the so-called temperature term in the description of Shubnikov-de Haas oscillations [61–63]. It is found that this effective mass is  $m_2 = (0.049 \pm 0.007)m_e$ , where  $m_e$  denotes the free-electron mass. From the magnetotransport measurements, it is thus concluded that two carrier populations contribute to transport: an electron population with lower mobility and higher density ( $N_{S1} = 8.50 \times 10^{16} \text{ m}^{-2}$ ) and a population of unknown type but with higher mobility and lower density ( $N_{S2} = 5.67 \times 10^{15} \text{ m}^{-2}$ ) and with an effective mass of  $m_2 = (0.049 \pm 0.007)m_e$ .

Extraction of the effective mass of the higher mobility carriers is independently corroborated by way of electron-cyclotron-resonance (CR) analysis under high magnetic field. Figure 5(a) displays the normalized transmission traces,  $T_B/T_0$ , at fixed magnetic fields ranging from 7 to 17 T, as a function of energy, demonstrating the evolution of the effective mass. Broad resonances are

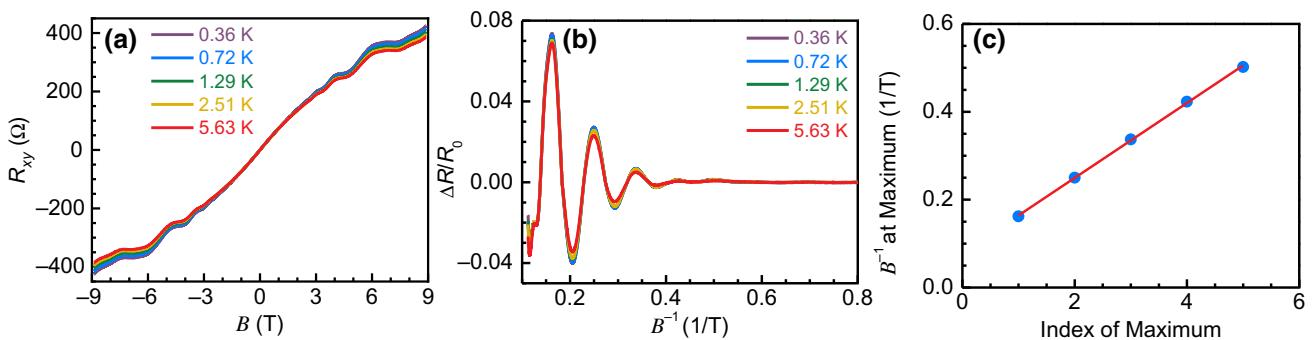


FIG. 4. (a) Transverse magnetoresistance ( $R_{xy}$  vs magnetic field, i.e., Hall effect) obtained in a van der Pauw configuration over temperatures 0.36 to 5.63 K and over magnetic fields  $\pm 9$  T. Shubnikov-de Haas oscillations are visible at higher magnetic fields due to intermixing with longitudinal magnetoresistance. (b) Shubnikov-de Haas oscillations plotted versus inverse magnetic field. (c) Inverse magnetic field (symbols, blue) at the maxima in (b) versus the index of the maxima, with a linear fit (solid line, red) displaying slope  $S = (0.0853 \pm 0.001) \text{ T}^{-1}$ .

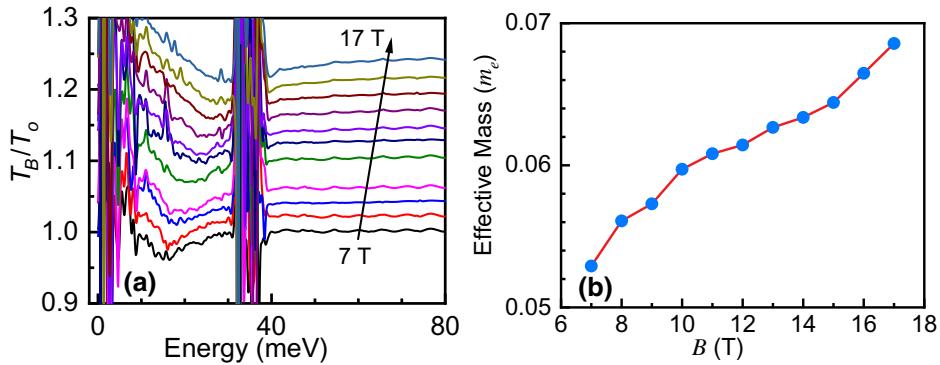


FIG. 5. (a) Normalized magnetotransmission traces,  $T_B/T_0$ , at fixed magnetic fields ranging from 7 to 17 T, as a function of energy; notably, traces are shifted for clarity. (b) Evolution of effective mass as a function of magnetic field, extracted from the resonance positions of the CR measurements, taken at 4.5 K (line is a guide for the eye).

observed as a result of the CR mobility of the carrier population being probed; however, extraction of the carrier effective mass as a function of the applied magnetic field, utilizing the measured resonance positions, is still possible, as shown in Fig. 5(b). The resulting effective

mass at  $B \approx 8$  T,  $m^* = 0.056m_e$ , is found to be in good agreement with that determined *via* the temperature dependence of the Shubnikov-de Haas oscillations. The increase in  $m^*$  with increasing  $B$  is due to the nonparabolicity effect in the conduction band of  $\varepsilon$ -Ge. Similar observations

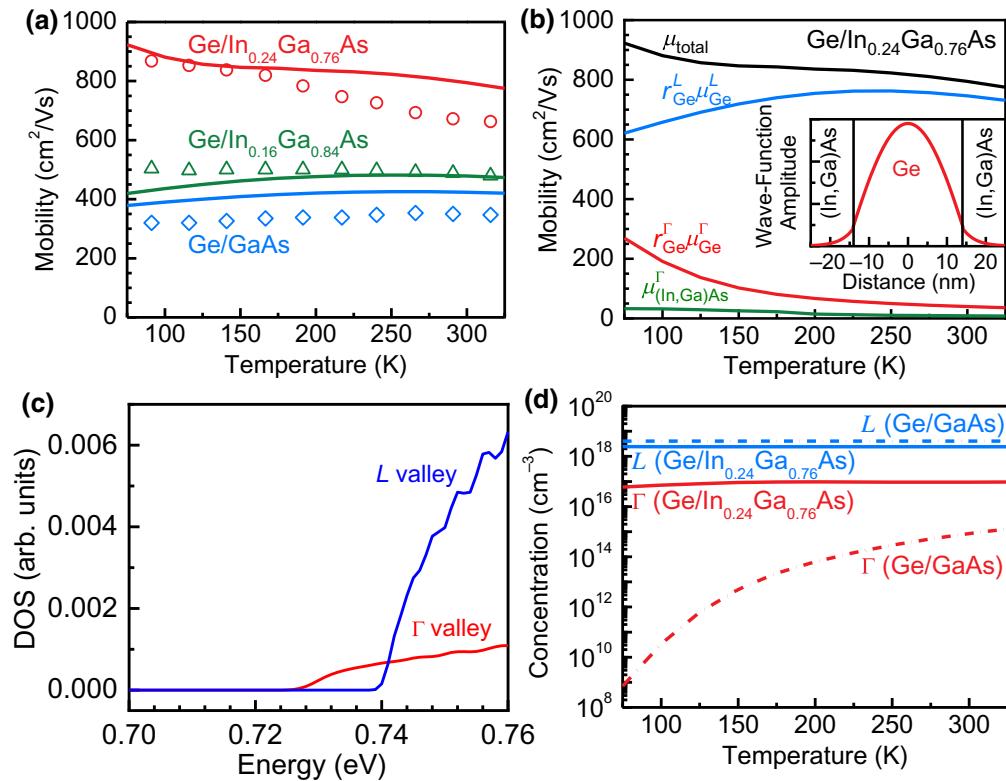


FIG. 6. (a) Measured (symbols) and calculated (solid lines)  $n$ -type mobility versus temperature in quantum-confined  $\varepsilon$ -Ge/In<sub>x</sub>Ga<sub>1-x</sub>As heterostructures for InAs mole fractions of 0, 0.16, and 0.24. Thicknesses of the Ge regions are (i) 80 nm, (ii) 15 nm, and (iii) 30 nm, for the 0, 0.16, and 0.24 In<sub>x</sub>Ga<sub>1-x</sub>As alloys, respectively [25]. (b) Temperature dependence of the calculated contributions to the total mobility from the  $L$  and  $\Gamma$  valleys in the  $\varepsilon$ -Ge region and the  $\Gamma$  valley in the  $In_{0.24}Ga_{0.76}As$  virtual substrate. Total mobility is given by  $\mu_{\text{total}} = \sum_j r_j \mu_j$ , where  $r_j = n_j/n_{\text{total}}$  is the proportion of carriers in valley  $j$ . (c) DOS versus energy of  $L$  and  $\Gamma$  valleys, showing higher DOS in the  $L$  valley than in the  $\Gamma$  valley. (d) Temperature dependence of the calculated volumetric carrier concentrations in the  $L$  and  $\Gamma$  valleys of  $\varepsilon$ -Ge and the  $\Gamma$  valley of  $In_{0.24}Ga_{0.76}As$  for the 1.6%  $\varepsilon$ -Ge/ $In_{0.24}Ga_{0.76}As$  heterostructure.

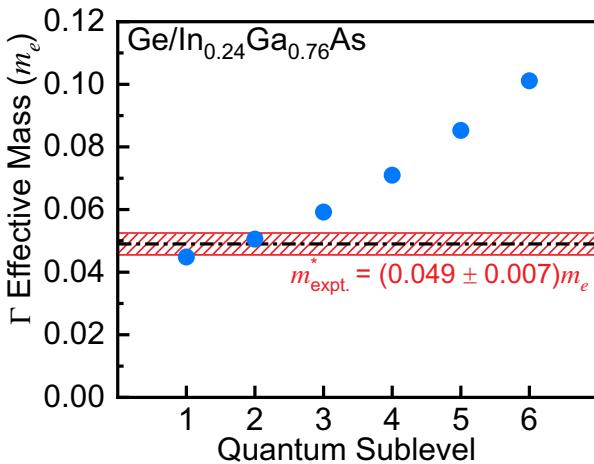


FIG. 7. Evolution of the  $\varepsilon$ -Ge  $\Gamma$ -valley effective mass with increasing quantum sublevel for the 1.6%  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterostructure at  $T=0$  K.

are reported in the literature for several material systems [64–71] due to nonparabolicity in the conduction band for *n*-type materials or in the valence band for *p*-type materials. However, neither measurement alone is sufficient to determine the carrier type of the higher mobility carriers. As such, electronic transport modeling of the  $\varepsilon$ -Ge/In<sub>x</sub>Ga<sub>1-x</sub>As material system is employed to provide additional insight into the empirical transport behavior.

### C. Modeling of the strain-dependent electronic transport properties of Ge

To clarify the origin of the Shubnikov-de Haas oscillations and carrier effective mass previously probed, the mobility in several  $\varepsilon$ -Ge/In<sub>x</sub>Ga<sub>1-x</sub>As heterostructures is calculated using a parametrization of the Boltzmann transport equation based on first principles [20]. The temperature-dependent Hall mobility measurements of unstrained and tensile-strained Ge samples (see Table I) are performed using the van der Pauw geometry to determine the carrier density and mobility of each sample. Figure 6(a) shows the mobility calculated as a function of temperature for three different strain states, corresponding to Ge grown on GaAs, In<sub>0.16</sub>Ga<sub>0.84</sub>As, and In<sub>0.24</sub>Ga<sub>0.76</sub>As alloys, as compared to experiments. The carrier densities for these layers are about  $4 \times 10^{18}$ ,  $7 \times 10^{18}$ , and  $2 \times 10^{18} \text{ cm}^{-3}$ , respectively. The symbols in this figure represent Hall mobility data, and the calculated solid lines are fitted to experimental results. To fit the experimental data of the Ge/AlAs sample (0% strain), a higher scattering rate for impurities is assumed since the measured mobility is quite low.

The *n*-type mobility ( $N_e \approx 2 \times 10^{18} \text{ cm}^{-3}$ ) exhibits contributions from the  $L$  and  $\Gamma$  valleys in the  $\varepsilon$ -Ge region (1.6%  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As), as well as the  $\Gamma$  valley in the In<sub>x</sub>Ga<sub>1-x</sub>As VS [Fig. 6(b)]; notably, the contribution

from each valley is proportional to the amplitude of the wave function (of the corresponding valley) in each region. For biaxial tensile strains lower than 1.6%, all conduction is found to occur *via* the  $L$  valley in Ge. At strain states above 1.6%, the contribution from the  $\Gamma$  valley is found to increase, particularly at low (<150 K) temperatures. Figure 6(b) shows the contribution from each valley to the total mobility in the 1.6%  $\varepsilon$ -Ge/In<sub>0.24</sub>Ga<sub>0.76</sub>As heterostructure. While transport primarily occurs *via* the  $L$  valley, at  $T=100$  K, the contribution of  $\Gamma$ -valley transport to the total mobility increases to 17%, diminishing with increasing temperature to approximately 3% at  $T=300$  K. These results can be explained by the much larger density of states within the  $L$  valley (i.e., the DOS masses of the  $L$  and  $\Gamma$  valleys are  $m_L^{\text{DOS}} = 0.22 m_e$  and  $m_{\Gamma}^{\text{DOS}} = 0.05 m_e$ , respectively), which became increasingly populated with rising temperature. Figure 6(c) shows the calculated DOS versus energy in both  $L$  and  $\Gamma$  valleys under 1.6% tensile strain. One can find from this figure that the DOS in the  $\Gamma$  valley is lower than that of  $L$  valley and most of the carriers will still reside within the  $L$  valley. Additionally, in spite of the high electron mobility of the In<sub>0.24</sub>Ga<sub>0.76</sub>As VS, it contributes comparatively little to the total mobility, owing to wave-function confinement within the  $\varepsilon$ -Ge region [Fig. 6(b), inset]. However, due to the smaller DOS of the  $\Gamma$  valley in Ge, such quantum confinement tends to decrease the mobility contribution of  $\Gamma$ -valley carriers to the total electron mobility, as compared to carriers residing in the higher DOS  $L$  valley in Ge. At room temperature, the carriers will populate both valleys, with more at the  $L$  valley than at the  $\Gamma$  valley due to higher DOS. The two ways one can increase the carrier density in the  $\Gamma$  valley are (i) by injecting carriers from the  $L$  valley by incorporating doping in the  $\varepsilon$ -Ge layer or (ii) during the lasing process by electrical injection [72].

Relating the transport modeling results to the aforementioned magnetotransport analysis, it is found that the measured electron population with a higher density ( $N_{S1}=8.50 \times 10^{16} \text{ m}^{-2}$ ) corresponds well to  $L$ -valley electron conduction in  $\varepsilon$ -Ge, whereas the lower population-density carriers ( $N_{S2}=5.67 \times 10^{15} \text{ m}^{-2}$ ), exhibiting an effective mass of  $m_2=(0.049 \pm 0.007)m_e$ , represent  $\Gamma$ -valley electron conduction in  $\varepsilon$ -Ge. A comparison of the calculated carrier populations in the  $L$  and  $\Gamma$  valleys of Ge and In<sub>x</sub>Ga<sub>1-x</sub>As as a function of temperature [Fig. 6(d)] yield qualitative agreement with empirical magnetotransport data. Moreover, calculation of the  $\Gamma$ -valley transport effective mass in 1.6%  $\varepsilon$ -Ge (Fig. 7) reveals excellent agreement between the effective masses of the first-two quantum sublevels ( $0.045m_e$  and  $0.051m_e$ , respectively) and that measured by experiments. As such, it can thus be posited that the effective mass of the relatively higher mobility carriers probed *via* the magnetotransport and CR studies corresponds to electrons residing in the first-two energy levels of the  $\Gamma$  valley in  $\varepsilon$ -Ge. Taken as a whole,

however, these results indicate that  $\varepsilon > 1.6\%$  is likely to be necessary to increase  $\Gamma$ -valley occupancy and, therefore, enhance the  $\Gamma$ -valley contribution to the total  $\varepsilon$ -Ge mobility.

#### IV. CONCLUSIONS

We provide a fundamental insight into the nature of electronic transport in highly tensile-strained Ge materials, along with their detailed structural analysis by x-ray, Raman, and cross-section and plan-view transmission electron microscopy. The quantification of defects and surface roughness are provided in the Supplemental Material [46]. The presented magnetotransport and cyclotron-resonance results, when coupled with our first-principles-parameterized Boltzmann transport modeling, reveal the strain dependence of  $L$ - and  $\Gamma$ -valley conduction in tensile-strained Ge. The temperature dependence of the calculated mobility and carrier contributions in each valley of  $1.6\% \varepsilon$ -Ge are decoupled based on the experimental Hall measurement results, and most of the carriers will reside within the  $L$  valley due to a higher density of states. In addition, the effective mass,  $m^* \approx 0.056m_e$ , determined *via* cyclotron resonance is in agreement with Shubnikov-de Haas oscillations. Moreover, the temperature-dependent competitiveness between  $L$ - and  $\Gamma$ -valley conduction in tensile-strained Ge has significant importance for future electron devices, such as strained Ge-based gate-all-around nanowire FETs [13,15] and tunnel FETs [19,24], wherein epitaxial strain is a key mechanism for improving carrier mobility and a device's drive current. Our results, however, are not limited to Ge-based electronics, as we also demonstrate direct experimental probing of the electron effective mass in Ge under high strain, thereby allowing for comparison with current and previous theoretical results [11,17–19].

#### ACKNOWLEDGMENTS

M.C. acknowledges financial support from the NSF under Grant No. ECCS-1348653. M.H. acknowledges partial support from the NSF under Grant No. ECCS-ECCS-2042079, a US-Ireland joint R&D program. G.A.K. acknowledges support from the Air Force Office of Scientific Research under Grant No. FA9550-17-1-0341. F. M. A. acknowledges financial support from Science Foundation Ireland Frontiers of the Future Program SFI/19/FFP/6953 and the US-Ireland R&D Partnership Program by Science Foundation Ireland (SFI) Grants No. SFI/20/US/3692 and SFI/14/US/I3057. The authors also acknowledge the NCFL Institute for Critical Technology and Applied Science and Virginia Tech Nanofabrication for providing material characterization facilities. M.C. and M.H. would also like to acknowledge Dr. Patrick Goley for assisting with the TEM imaging. Lastly, a portion of this

work is performed at the National High Magnetic Field Laboratory, which is supported by the National Science Foundation Cooperative Agreement No. DMR-1157490 and the State of Florida.

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